





## 1. Description

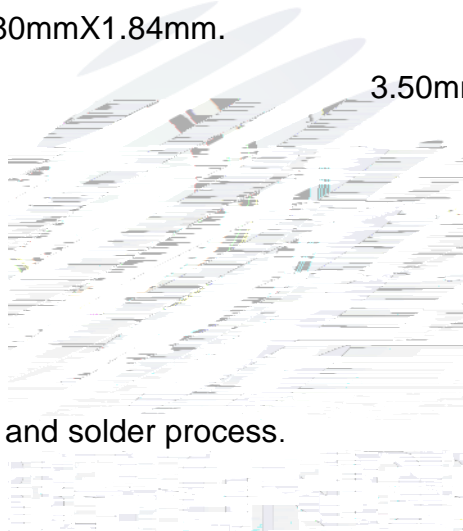
### 1.1

The Amber source color devices are made with AlGaInp on Substrate Light Emitting Diode .

Product Package:3.50mmX2.80mmX1.84mm.

GaN

3.50mmX2.80mmX1.84mm.



### 1.2 Features

PLCC2 Package.

Extremely wide viewing angle.

Suitable for all SMT assembly and solder process.

Available on tape and reel.

Moisture sensitivity level: Level 2.

### 1.4 Package Dimension

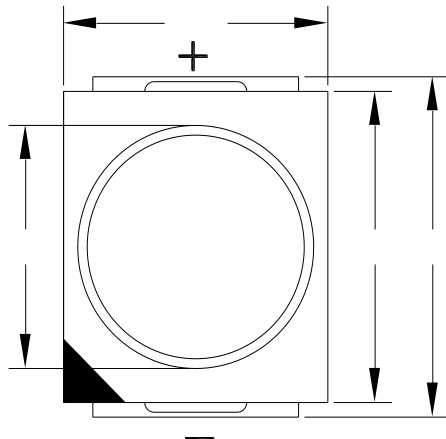


Fig.1-1 Top View

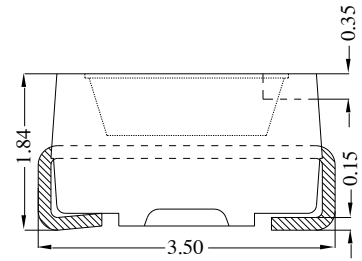


Fig.1-2 Side View

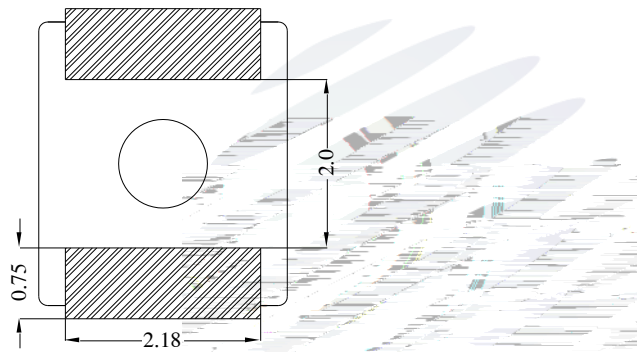


Fig.1-3 Bottom View

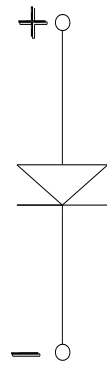


Fig.1-4 Polarity

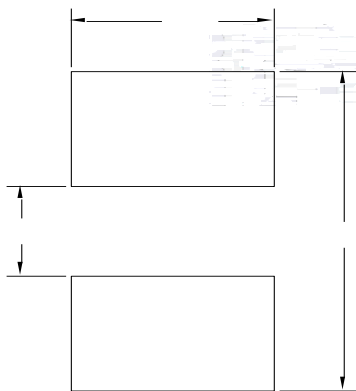
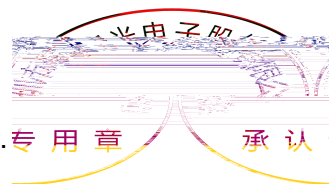


Fig.1-5 Soldering Patterns

#### Notes

All dimensions units are millimeters.

All dimensions tolerances are  $\pm 0.2\text{mm}$  unless otherwise noted. 专用章 承认:  $\pm$







## 1.7 Typical Optical Characteristics Curves

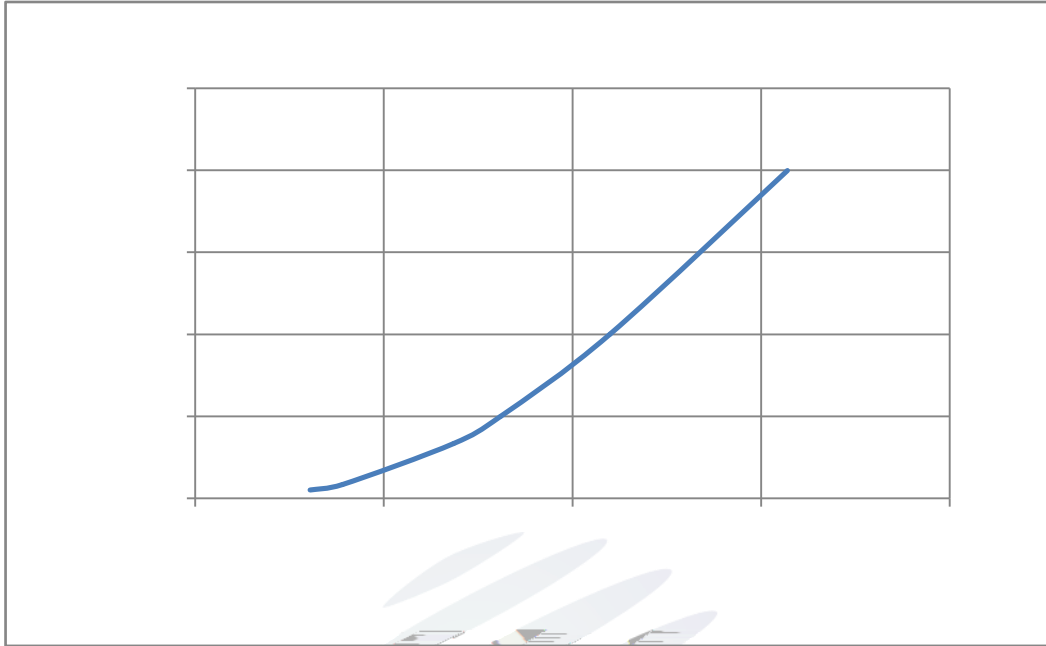


Fig. 1-7 Forward Voltage Vs Forward Current

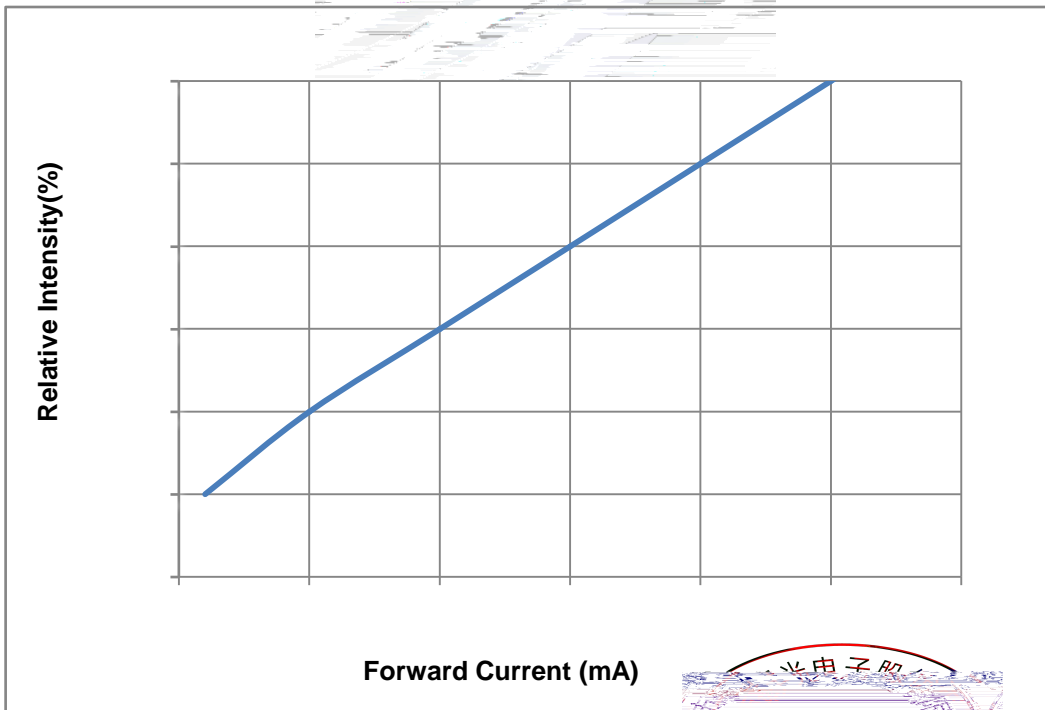
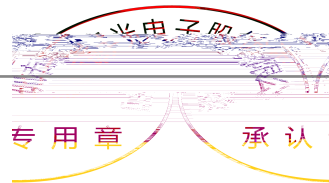


Fig. 1-8 Forward Current Vs Relative Intensity



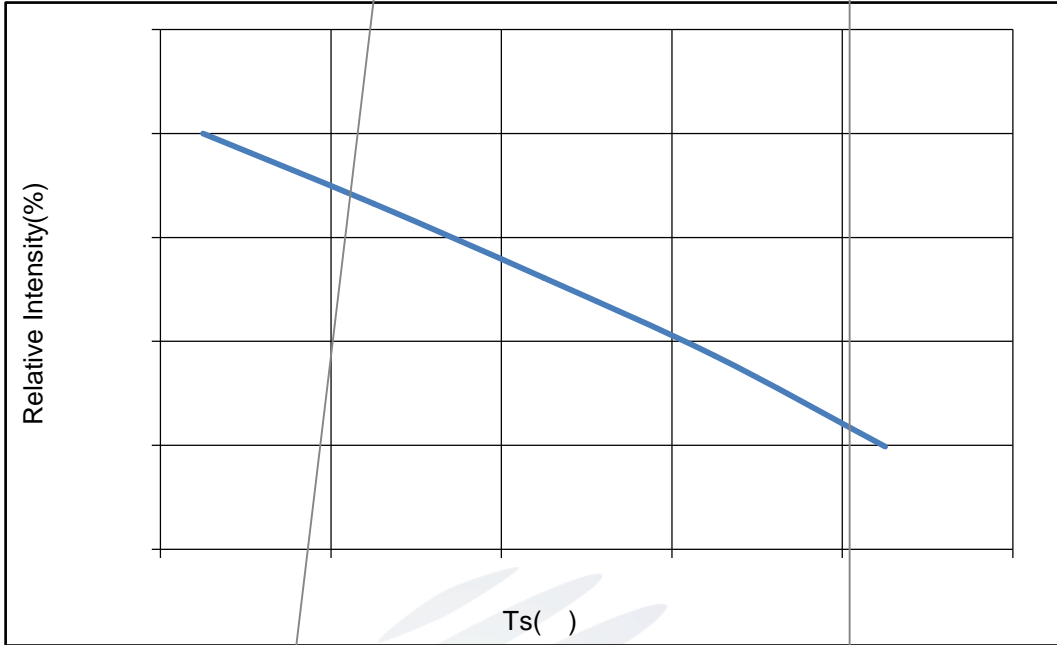


Fig. 1-9 Solder Temperature Vs Relative Intensity



Fig. 1-10 Solder Temperature Vs Forward Current



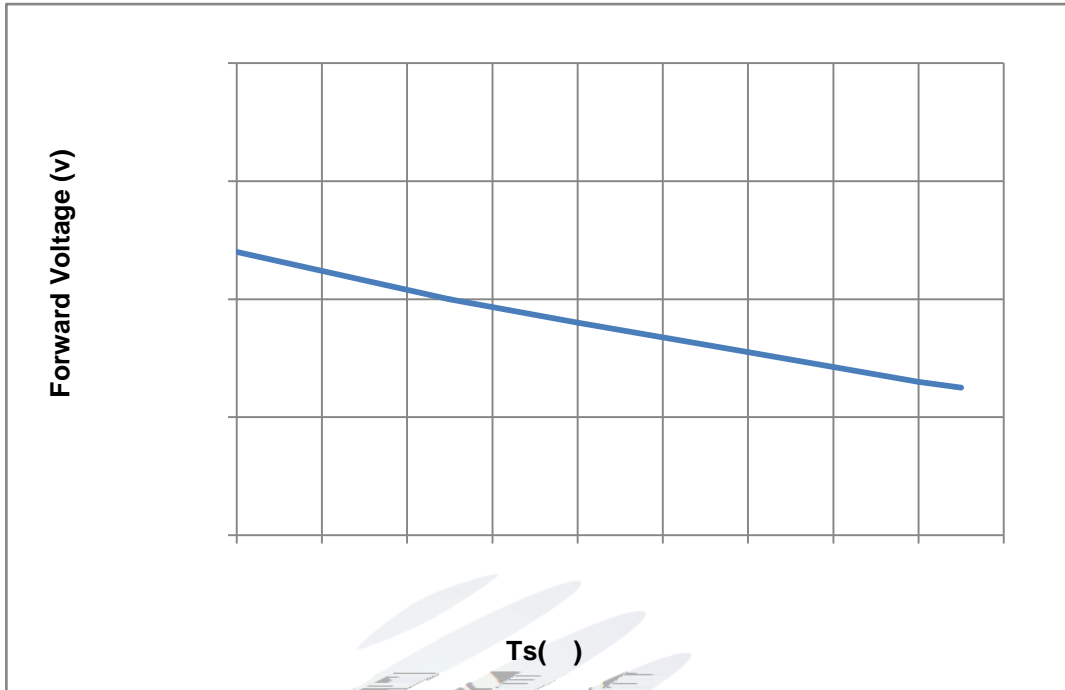


Fig. 1-11 Forward Voltage Vs Solder Temperature

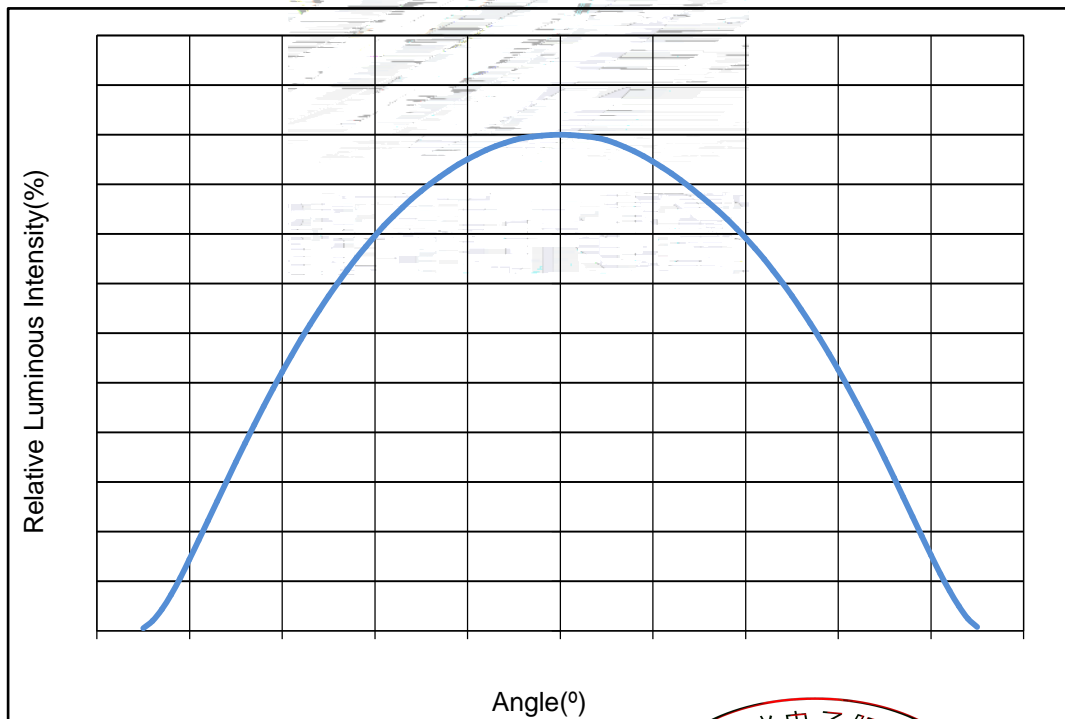
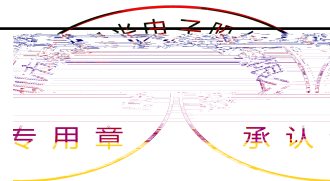


Fig. 1-12 Radiation diagram



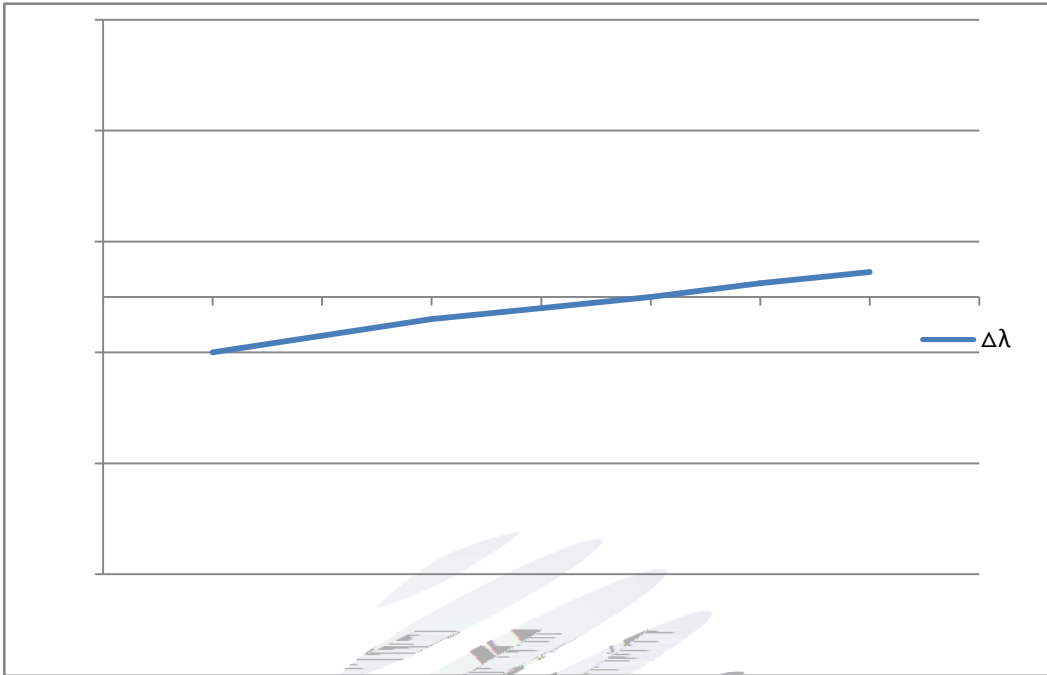


Fig. 1-13 Forward current vs. Dominate wavelength (Ts=25°C)

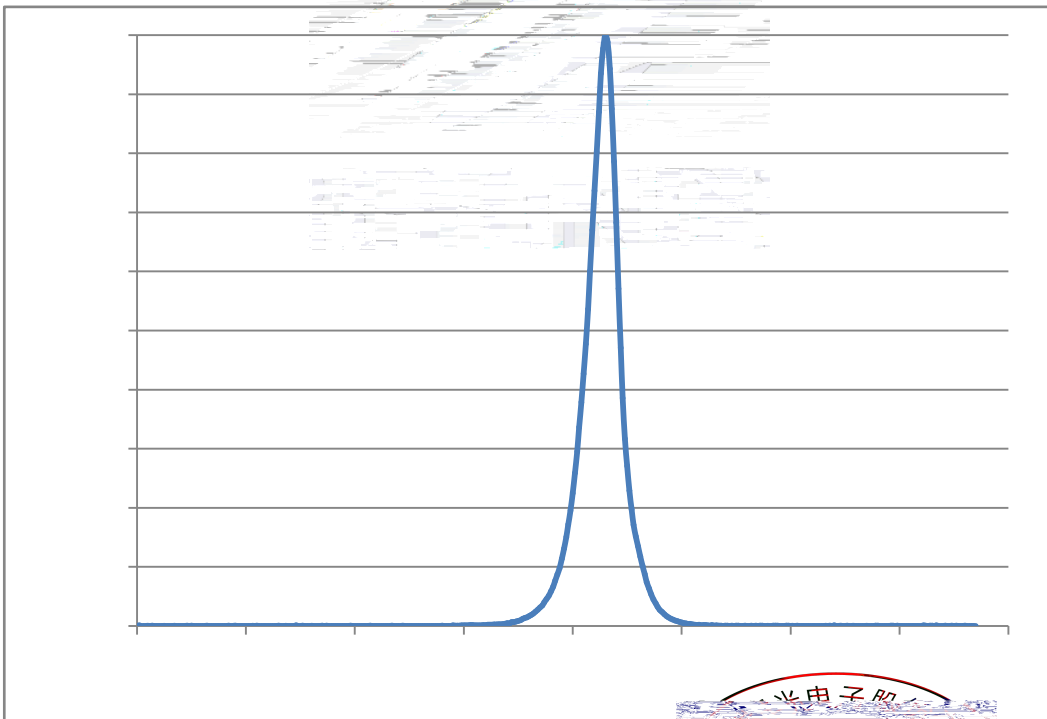
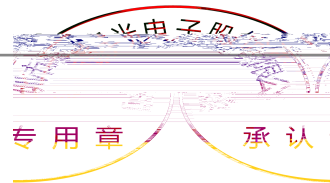


Fig. 1-14 Spectrum Distribution



## 2. Packaging

### 2.1 Packaging Specification

Package:2000pcs/reel.

#### 2.1.1 Carrier Tape Dimension

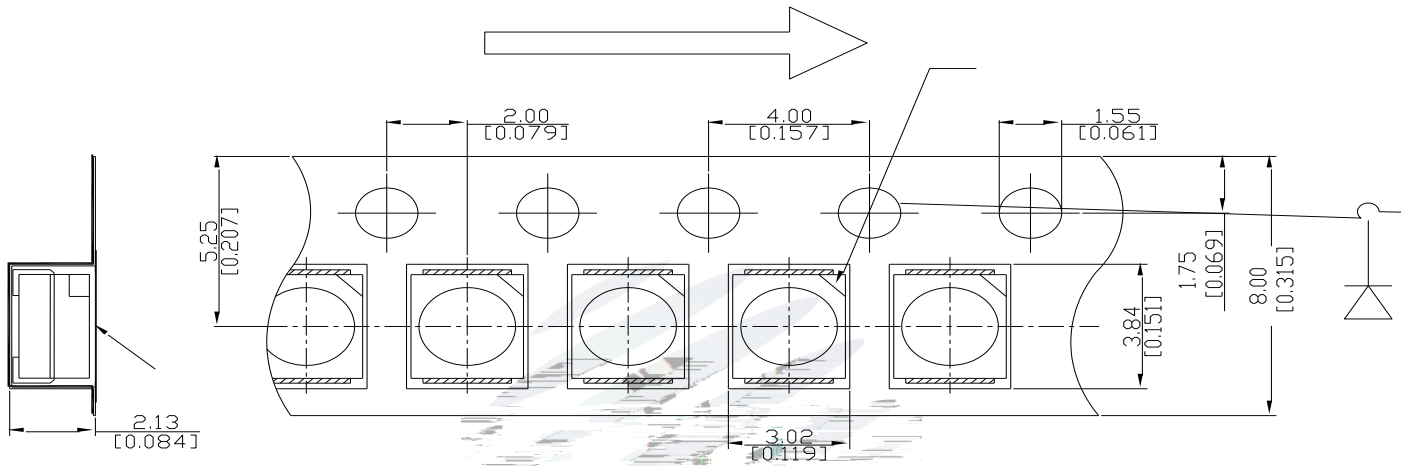


Fig.2-1 Carrier Tape Dimension

#### 2.1.2 Reel Dimension

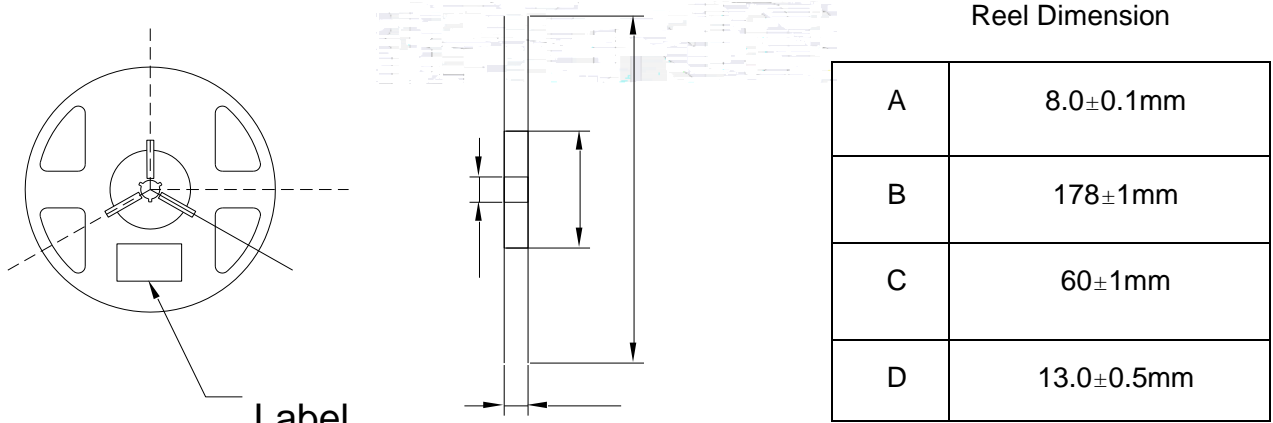
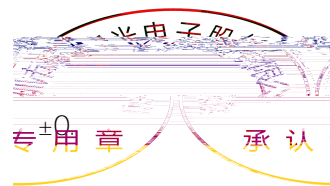


Fig.2-2 Reel Dimension

#### Notes

The tolerances unless mentioned ±0.1mm. Unit : mm



### 2.1.3 Label Form Specification

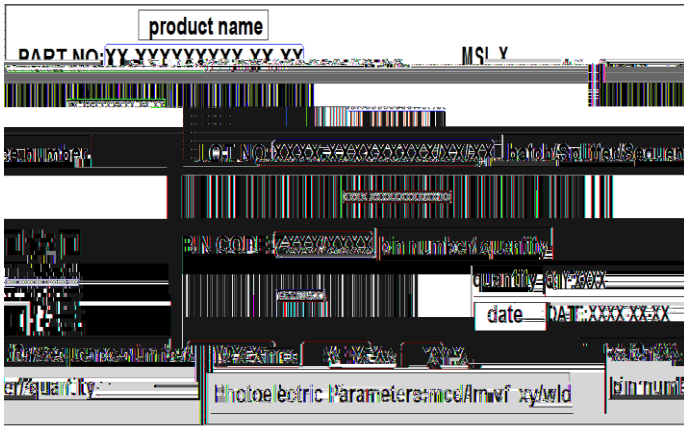


Fig. 2-3 Label Form Specification

#### Specification

|                |                  |
|----------------|------------------|
| PART NO.       | Part Number      |
| SPEC NO.       | Spec Number      |
| LOT NO.        | Lot Number       |
| BIN CODE       | Bin Code         |
|                | Luminous flux    |
| XY             | Chromaticity Bin |
| V <sub>F</sub> | Forward Voltage  |
| WLD            | Wavelength       |
| QTY            | Packing Quantity |
| DATE           | Made Date        |

### 2.2 Moisture Resistant Packing

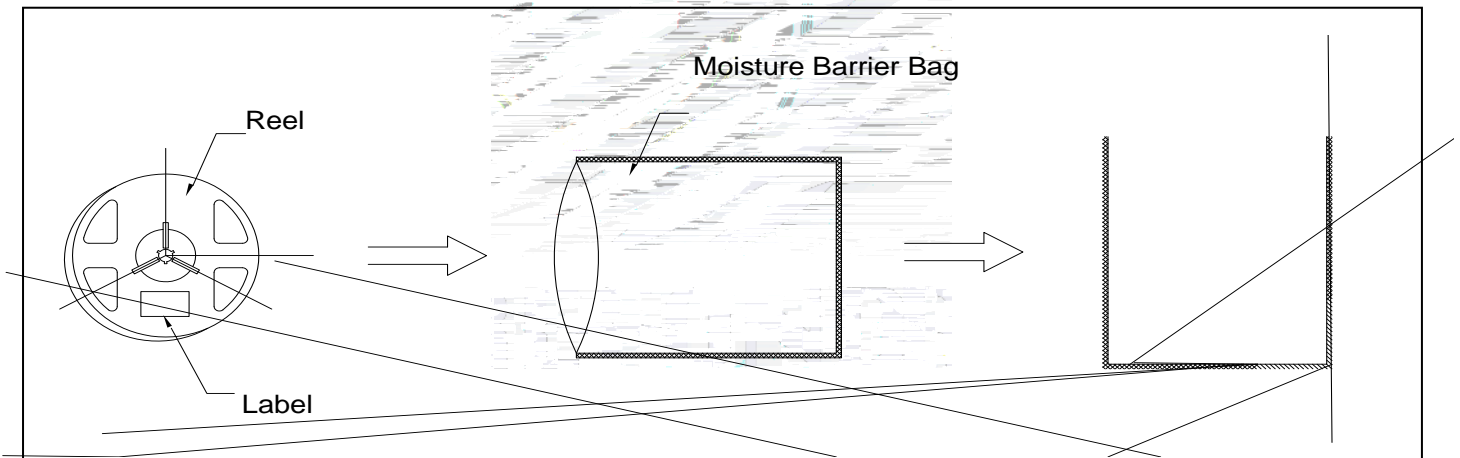
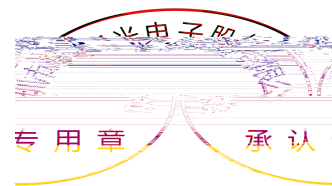


Fig.2-4 Moisture Resistant Packing



## 2.3 Cardboard Box

Fig.2- Cardboard Box

## 2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

| Test Items | Ref.Standard | Test Condition | Time | Quantity | Ac/Re |
|------------|--------------|----------------|------|----------|-------|
| Reflow     | JESD22-B106  | Temp:260       |      |          | /     |

|   |                          |   |          |        |     |
|---|--------------------------|---|----------|--------|-----|
| High Temperature<br>High Humidity Life Test | JESD22-A101              | 85 / 85%RH<br>I <sub>F</sub> =20mA        | 1000hrs. | 20pcs. | 0/1 |
| Temperature<br>Humidity Storage             | JEITA ED-4701<br>100 103 | T <sub>A</sub> =85<br>R <sub>H</sub> =85% | 1000hrs. | 20pcs. | 0/1 |

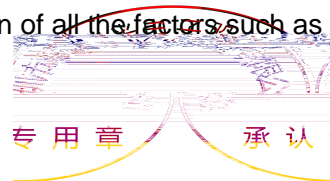
## 2.5 Criteria For Judging Damage

Table 2-4 Criteria For Judging Damage

| Test Items      | Symbol         | Test Condition       | Criteria For Judgement |             |
|-----------------|----------------|----------------------|------------------------|-------------|
|                 |                |                      | Min.                   | Max.        |
| Forward Voltage | V <sub>F</sub> | I <sub>F</sub> =20mA | -                      | U.S.L*)x1.1 |
| Reverse Current | I <sub>R</sub> | V <sub>R</sub> = 5V  | -                      | U.S.L*)x2.0 |
| Luminous Flux   |                | I <sub>F</sub> =20mA | L.S.L*)x0.7            | -           |

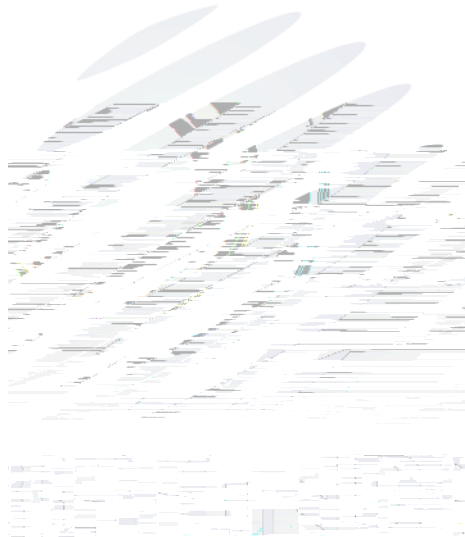
### Notes

- 1.U.S.L: Upper standard level                      L.S.L: Lower standard level
- 2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others.

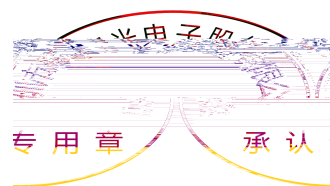




|  |    |                       |
|--|----|-----------------------|
| Time limit classification of peak temperature time |    |                       |
| $t_p$  | 10 | Max 10s               |
| ( $T_P$ ) 5 °C                                     |    | Hold time within 5 °C |
| with the actual peak temperature (TP)              | 30 |                       |







energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor.

(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

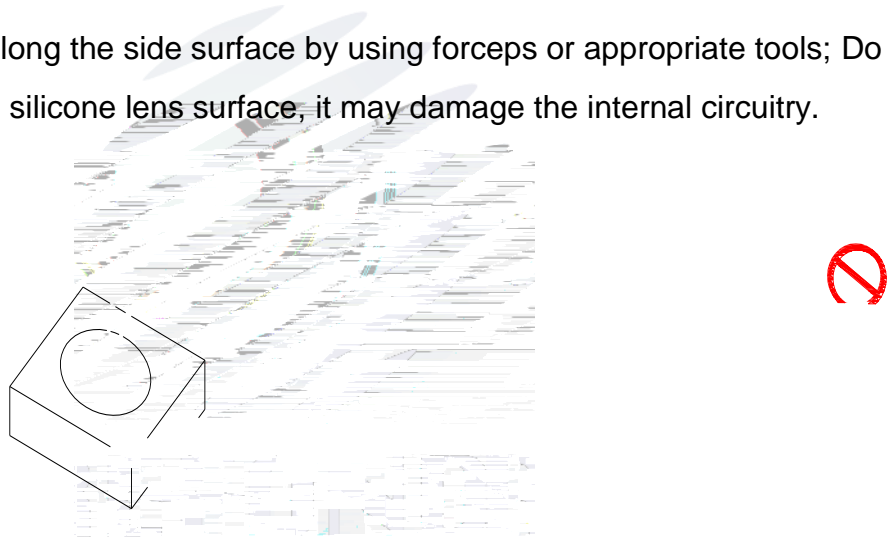
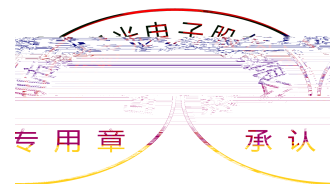


Fig 4-1 Handling Precautions

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the mean while, resistors for protection should be applied, other wise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.



(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.



Table 4-1 Storage

| Conditions |                             | Temperature | Humidity | Time                                |
|------------|-----------------------------|-------------|----------|-------------------------------------|
| Storage    | Before Opening Aluminum Bag | 30          | 75%      | Within 1 Year From Date             |
|            | After Opening Aluminum Bag  | 30          | 60%      | Recommended for use within 24 hours |
| Baking     |                             | 60±5        | -        | 24hours<br>24                       |

(8) If the moisture absorbent material silica gel has faded away or the

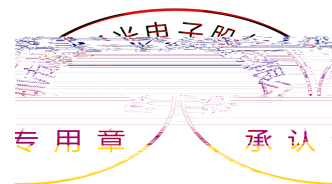
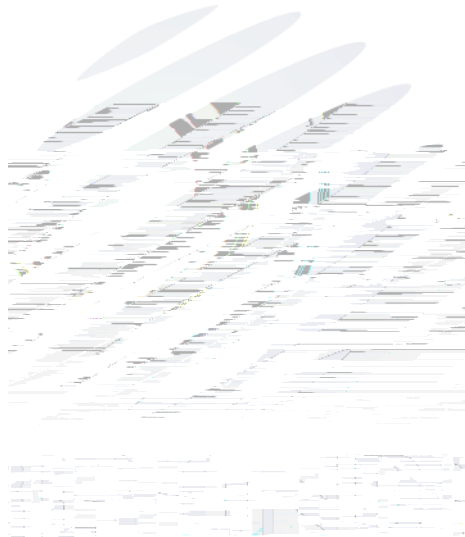
following condition 65 5 for above 24 hours.

±

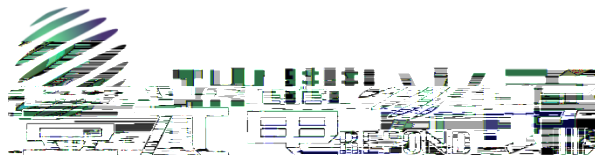
If the package is flatulence or damaged, please notify the sales staff to assist.

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

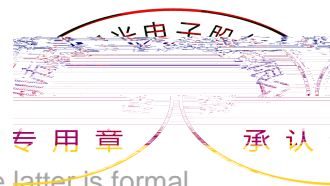
(10) Other points for attention, please refer to our relevant information.







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Declare

This specification is written both in English and in Chinese and the latter is formal.